

SMD0805 Series

Surface-Mount Low Resistance PTC Device
 Rev Letter: A/T
 Rev Date: 2016-12-1



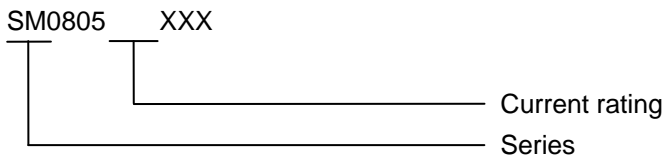
Feature

- Resettable overcurrent protection
- Very Low resistance
- High current rating
- Fast time-to-trip
- Small footprint
- ROHS compliant and Halogen free

Application

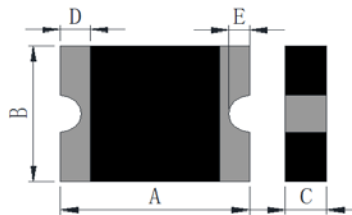
- Mobile phone battery packs
- Cordless phone battery packs
- Mobile radio packs
- Computer battery packs
- Camcorder battery packs
- PDA battery packs

Part Number



Typical Ratings and Characteristics

Part Number	HOLD CURRENT & TRIP CURRENT (AMPS)		V _{max} /I _{max}	TIME-TO-TRIP (SECONDS)	REFERENCE RESISTANCE (OHMS)	TWO HOURS POST REFLOW RESISTANCE (OHMS)	TRIPPED STATE POWER DISSIPATION (WATTS)
	25°C		25°C	25°C	25°C	25°C	25°C
	HOLD	TRIP	V/A	MAX	MIN	MAX	MAX
SMD0805-035	0.35	1.00	6/100	8.0A/0.5S	0.024	0.086	0.8
SMD0805-050	0.50	1.20	6/100	8.0A/0.5S	0.020	0.080	1.0
SMD0805-075	0.75	2.00	6/40	8.0A/0.5S	0.018	0.076	1.0
SMD0805-100	1.00	3.00	6/40	5.0A/5.0S	0.017	0.072	1.0
SMD0805-110	1.10	3.50	6/100	5.5A/5.0S	0.017	0.070	1.0
SMD0805-150	1.50	4.50	6/50	7.5A/5.0S	0.016	0.068	1.0
SMD0805-175	1.75	5.50	6/50	8.0A/5.0S	0.015	0.060	1.0
SMD0805-200	2.00	4.00	6/50	10.0A/5.0S	0.013	0.056	1.0



*The max resistance of two-hours post reflow is a reference value. The value maybe changes a little according to reflow conditions and soldering state.

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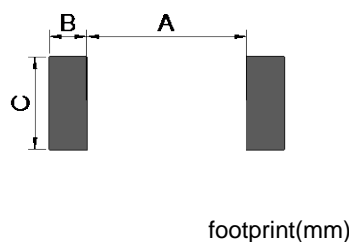
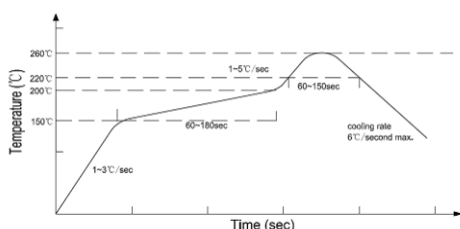
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Product Dimension and Foot Print

	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
	Max	Max	Max	Min	Min
SMD0805-035	2.3	1.5	0.8	0.2	0.05
SMD0805-050	2.3	1.5	0.8	0.2	0.05
SMD0805-075	2.3	1.5	0.8	0.2	0.05
SMD0805-100	2.3	1.5	0.8	0.2	0.05
SMD0805-110	2.3	1.5	0.8	0.2	0.05
SMD0805-150	2.3	1.5	0.8	0.2	0.05
SMD0805-175	2.3	1.5	0.8	0.2	0.05
SMD0805-200	2.3	1.5	0.8	0.2	0.05

Solder Reflow Recommendation



- * Recommended reflow methods: IR, hot air oven, nitrogen oven
- * Recommended maximum paste thickness: 0.25mm (0.010 inch)
- * Devices can be cleaned using standard industry methods and solvents.
- * Solder temperature and time should be controlled strictly in recommended conditions.

Note:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Caution: Operation beyond the rated voltage or current may result in rupture electrical arcing or flame

Packaging and Marking Information

Part number	Tape & Reel		Part Marking	Recommended Pad Layout Figures(mm)		
	Quantity	Tape spc code		Dimension A	Dimension B	Dimension C
SMD0805-035	3500	0805B	F	1.80	1.00	1.80
SMD0805-050	3500	0805B	S	1.80	1.00	1.80
SMD0805-075	3500	0805B	E	1.80	1.00	1.80
SMD0805-100	3500	0805B	B	1.80	1.00	1.80
SMD0805-110	3500	0805B	B	1.80	1.00	1.80
SMD0805-150	3500	0805B	P	1.80	1.00	1.80
SMD0805-175	3500	0805B	K	1.80	1.00	1.80
SMD0805-200	3500	0805B	M	1.80	1.00	1.80

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WARNING:

- Operation beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.
- The devices are intended for protection against occasional overcurrent or over-temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- Contamination of the PPTC material with certain silicon based oils or some aggressive solvents can adversely impact the performance of the devices.
- Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal and mechanical procedures for electronic components.
- Operation in circuit with a large inductance can generate a circuit voltage ($L di/dt$) above the rated voltage of the PPTC device.

Prepare	Approval	Accept